

KB-6165 (ANSI: FR-4.0)**覆铜箔环氧玻纤布层压板****特点**

- Tg 150℃ (DSC 测试), 低 Z-轴 CTE 值
- 热裂解温度高
- 优良的耐热性, 能满足无铅制程要求
- 符合 IPC-4101C/124 的规范要求
- 非双氰胺固化体系, 不含填料
- 良好的耐金属离子迁移性

Features

- Tg150℃ (By DSC), low Z-axis expansion
- High Temperature of Decomposition (Td)
- Excellent heat resistance and appropriate for Lead Free Assembly.
- IPC-4101C/124 specification is applicable .
- Dicy –free and no filler
- ANTI-CAF

General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Method (IPC-TM-650) 测试方法	Test Condition 处理条件	Specification (IPC-4101C) 规格值	Typical Value 典型值
Peel Strength (1 oz.) 铜箔剥离强度	N/mm	2.4.8	125℃	≥ 0.70	1.35
			Float 288℃/ 10 Sec	≥ 1.05	1.42
Flammability 燃烧性	Rating	UL94	E-24/23	UL94 V-0	V-0
Thermal Stress 热应力	Sec	2.4.13.1	Float 288℃/unetched	≥ 10	60
Glass Transition (Tg) 玻璃转化温度	℃	2.4.25	E-2/105 DSC	≥ 150	153
Surface Resistivity 表面电阻	MΩ	2.5.17.1	C-96/35/90	≥ 1.0×10 ⁴	1.0×10 ⁷
Volume Resistivity 体积电阻	MΩ-cm	2.5.17.1	C-96/35/90	≥ 1.0×10 ⁶	1.0×10 ⁹
Moisture Absorption 吸水性	%	2.6.2.1	D-24/23	≤ 0.35(min0.51)	0.16
				≤ 0.80(max0.51)	0.30
Dielectric Breakdown 介质击穿	KV	2.5.6	D-48/50+D0.5/23	≥ 40	72
Dielectric Strength 介质强度	KV/mm	2.5.6.2	D-48/50+D0.5/23	≥ 29	46
Flexural Strength 抗弯强度	N/mm ²	2.4.4	Warp	≥ 415	560
			Fill	≥ 345	430
Dielectric Constant 介电常数	—	2.5.5.2	Etched/@1 MHZ	≤ 5.4	4.65
Loss Tangent 介质损耗	—	2.5.5.2	Etched/@1 MHZ	≤ 0.035	0.018
Arc Resistance 耐电弧性	Sec	2.5.1	D-48/50+D0.5/23	≥ 60	125
CTE Z-Axis Expansion	ppm/℃	2.4.24	E-2/105 TMA	≤ 60/300	55/287
	% (50-260℃)			≤ 3.5	3.1
TD	℃	2.4.24.6	TGA	≥ 325	339
CAF	H	-	85%, 85℃, 50V DC	≥ 1000	1000
T-260	min	2.4.24.1	TMA	≥ 30	50
T-288	min	2.4.24.1	TMA	≥ 5	23

Remarks: Specimen Thickness: 1.6 mm 样品厚度: 1.6 mm

A = Keep the specimen originally without any process 保持原样, 不作处理

C = Temperature and humidity conditioning 在恒温恒湿的空气中处理;

D = Immersing in distilled water with temperature control. 浸在恒温的水中处理;

E = Temperature conditioning 在恒温的空气中处理;

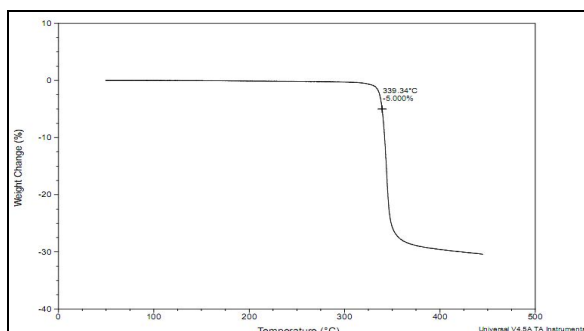
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Other data for references 其它数据(仅供参考)

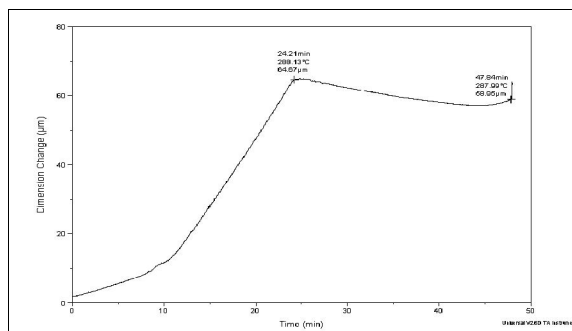
Item		Unit	Typical Value	Item		Unit	Typical Value
Young's modulus	Warp	Million	3.5	Poisson's ratio	Warp	--	0.14
	Fill	psi	3.2		Fill	--	0.13
Tailors modulus	Warp	Million	3.3	Tensile strength	Warp	N/mm ²	385
	Fill	psi	2.9		Fill		265

Speciality Chart 板材特性图

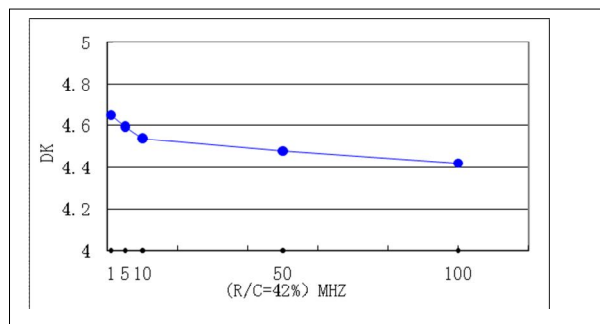
Td(TGA)=339.34℃



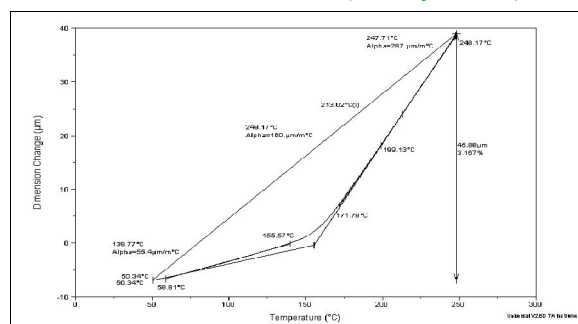
Delamination 分层时间(T-288 test by TMA)



Dielectric constant 介电常数



CTE Z 轴热膨胀系数 (test by TMA)

**Applications 应用领域**

- Computer, communication equipment, instrument, OA equipment, etc.
计算机及外围设备、通讯设备、仪器仪表、办公自动设备等

Purchasing Information 采购信息

Base Color 基板颜色	Thicknesses 厚度	Copper Cladding 铜箔厚度	Regular Sizes 常规尺寸
黄色 Yellow	0.05mm ~ 3.2mm	18μm /35μm 70μm /105μm	915*1220mm (36"*48") 1020*1220mm (40"*48") 1067*1220mm (42"*48")

Note: Other sheet size and thickness could be available upon request.

可根据客户要求提供其它尺寸和厚度